

NXP 74F125 buffer datasheet

<http://www.manuallib.com/nxp/74f125-buffer-datasheet.html>

The 74F125 provides four non-inverting buffer/line drivers with 3-state outputs. The 3-state outputs (nY) are controlled by the output enable input (nOE). A HIGH at nOE causes the outputs to assume a high-impedance OFF-state.

ManualLib.com collects and classifies the global product instruction manuals to help users access anytime and anywhere, helping users make better use of products.

<http://www.manuallib.com>

74F125

Quad buffers; 3-State

Rev. 4 — 23 January 2013

Product data sheet

1. General description

The 74F125 provides four non-inverting buffer/line drivers with 3-state outputs. The 3-state outputs (nY) are controlled by the output enable input ($\overline{\text{nOE}}$). A HIGH at $\overline{\text{nOE}}$ causes the outputs to assume a high-impedance OFF-state.

2. Features and benefits

- High impedance NPN base inputs for reduced loading (20 μA in HIGH and LOW states)

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
N74F125N	0 °C to +70 °C	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
N74F125D	0 °C to +70 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1



4. Functional diagram

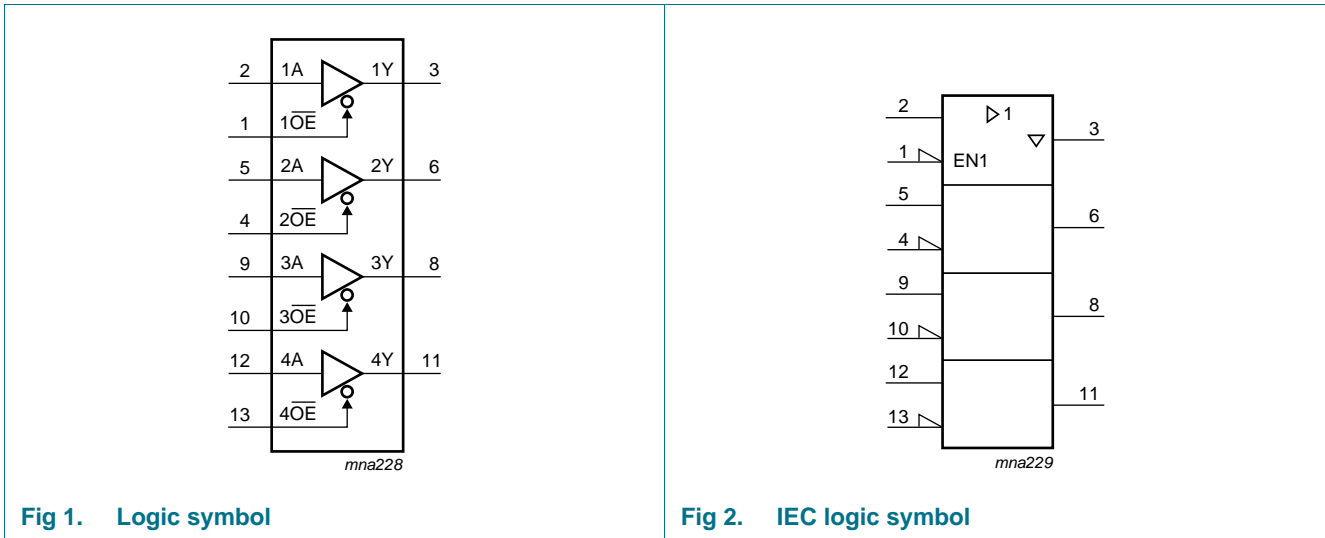


Fig 1. Logic symbol

Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning

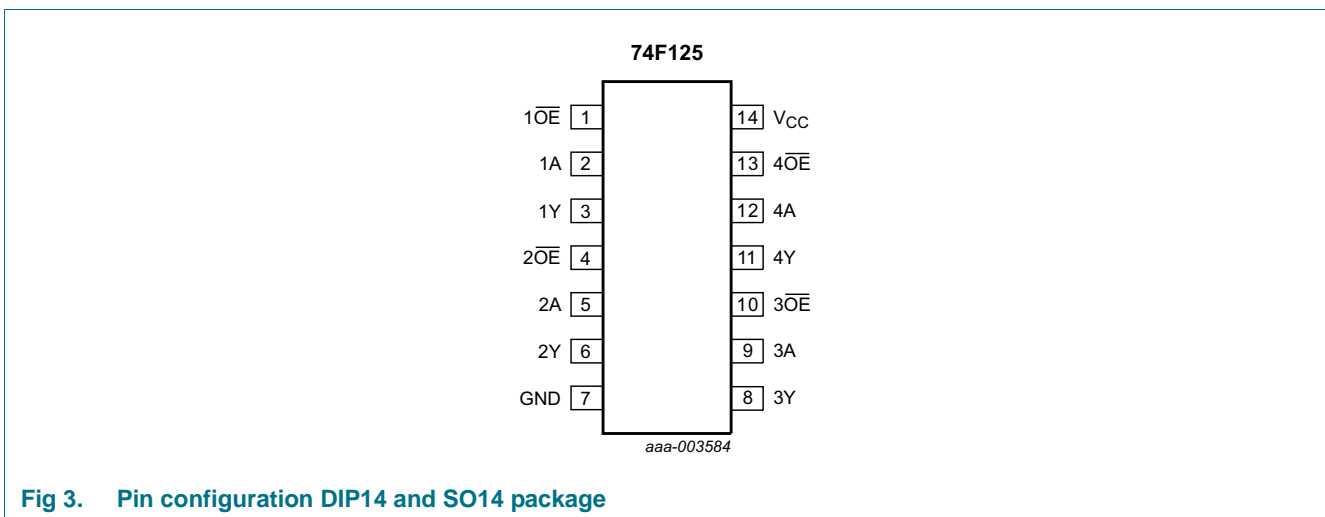


Fig 3. Pin configuration DIP14 and SO14 package

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description	Unit load HIGH/LOW	Load value ^[1] HIGH/LOW
$\overline{1OE}$ to $\overline{4OE}$	1, 4, 10, 13	output enable input (active LOW)	1.0/0.033	20 μ A/20 μ A
1A to 4A	2, 5, 9, 12	data input	1.0/0.033	20 μ A/20 μ A
1Y to 4Y	3, 6, 8, 11	data output	750/106.7	15 mA/64 mA
GND	7	ground (0 V)	-	-
V _{CC}	14	supply voltage	-	-

[1] One FAST Unit Load (UL) is defined as 20 μ A in HIGH state, 0.6 μ A in LOW state.

6. Functional description

Table 3. Function table^[1]

Control	Input	Output
nOE	nA	nY
L	L	L
	H	H
H	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7.0	V
V _I	input voltage		^[1] -0.5	+7.0	V
V _O	output voltage	output in HIGH-state	^[1] -0.5	V _{CC}	V
I _{IK}	input clamping current	V _I < 0 V	-30	+5	mA
I _O	output current	output in LOW-state	-	128	mA
T _{amb}	ambient temperature	in free air	^[2] 0	70	°C
T _{stg}	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
I_{IK}	input clamping current		-18	-	-	mA
I_{OH}	HIGH-level output current		-15	-	-	mA
I_{OL}	LOW-level output current		-	-	64	mA
T_{amb}	ambient temperature		0		70	°C

9. Static characteristics

Table 6. Static characteristics

Symbol	Parameter	Conditions	25 °C			0 °C to +70 °C		Unit	
			Min	Typ ^[1]	Max	Min	Max		
V_{IK}	input clamping voltage	$V_{CC} = 4.5 \text{ V}$; $I_{IK} = -18 \text{ mA}$	-1.2	-0.73	-	-1.2	-	V	
V_{OH}	HIGH-level output voltage	$V_{CC} = 4.5 \text{ V}$; $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$ $I_{OH} = -3 \text{ mA}$							
		$V_{CC} = \pm 10 \%$	-	-	-	2.4	-	V	
		$V_{CC} = \pm 5 \%$	-	3.3	-	2.7	-	V	
		$I_{OH} = -15 \text{ mA}$ $V_{CC} = \pm 10 \%$	-	-	-	2.0	-	V	
V_{OL}	LOW-level output voltage	$V_{CC} = 4.5 \text{ V}$; $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$ $I_{OL} = 64 \text{ mA}$							
		$V_{CC} = \pm 10 \%$	-	-	-	-	0.55	V	
		$V_{CC} = \pm 5 \%$	-	0.42	-	-	0.55	V	
I_I	input leakage current	$V_{CC} = 0 \text{ V}$; $V_I = 7.0 \text{ V}$	-	-	-	-	100	μA	
I_{IH}	HIGH-level input current	$V_{CC} = 5.5 \text{ V}$; $V_I = 2.7 \text{ V}$	-	-	-	-	20	μA	
I_{IL}	LOW-level input current	$V_{CC} = 5.5 \text{ V}$; $V_I = 0.5 \text{ V}$	-	-	-	-20	-	μA	
I_{OZ}	OFF-state output current	$V_{CC} = 5.5 \text{ V}$ $V_O = 2.7 \text{ V}$	-	-	-	-	50	μA	
		$V_O = 0.5 \text{ V}$	-	-	-	-50	-	μA	
I_O	output current	$V_{CC} = 5.5 \text{ V}$	^[2]	-	-	-	-225	-100	mA
I_{CC}	supply current	$V_{CC} = 5.5 \text{ V}$; $V_I = \text{GND}$ or V_{CC}							
		outputs HIGH-state	-	17	-	-	24	mA	
		outputs LOW-state	-	28	-	-	40	mA	
		outputs OFF-state	-	25	-	-	35	mA	

[1] All typical values are measured at $V_{CC} = 5 \text{ V}$.

[2] No more than one output should be tested at a time, and the duration of the test should not exceed one second.

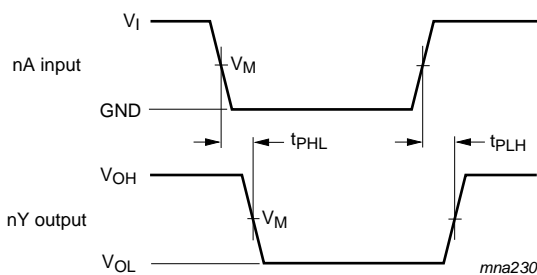
10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V. Test circuit is shown in Figure 6.

Symbol	Parameter	Conditions	25 °C; V _{CC} = 5.0 V			0 °C to +70 °C; V _{CC} = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t _{PLH}	LOW to HIGH propagation delay	nA to nY, see Figure 4	2.0	4.0	6.0	2.0	6.5	ns
t _{PHL}	HIGH to LOW propagation delay	nA to nY; see Figure 4	3.0	5.5	7.5	3.0	8.0	ns
t _{PZH}	OFF-state to HIGH propagation delay	n $\overline{\text{OE}}$ to nY; see Figure 5	3.5	5.5	7.5	3.5	8.5	ns
t _{PZL}	OFF-state to LOW propagation delay	n $\overline{\text{OE}}$ to nY; see Figure 5	4.0	6.0	8.0	4.0	9.0	ns
t _{PHZ}	HIGH to OFF-state propagation delay	n $\overline{\text{OE}}$ to nY; see Figure 5	1.5	3.5	5.0	1.5	6.0	ns
t _{PLZ}	LOW to OFF-state propagation delay	n $\overline{\text{OE}}$ to nY; see Figure 5	1.5	3.5	5.5	1.5	6.0	ns

11. Waveforms



$V_M = 1.5 \text{ V}$

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 4. Propagation delay input (nA) to output (nY)

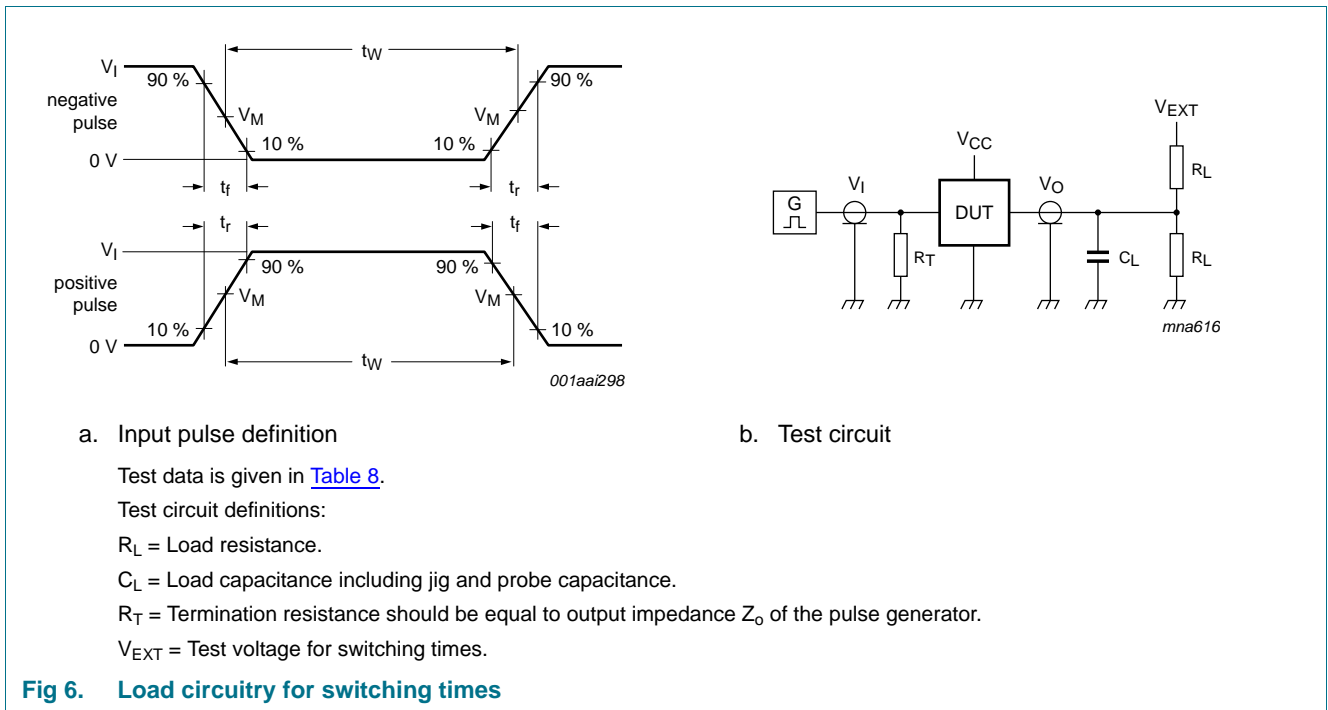
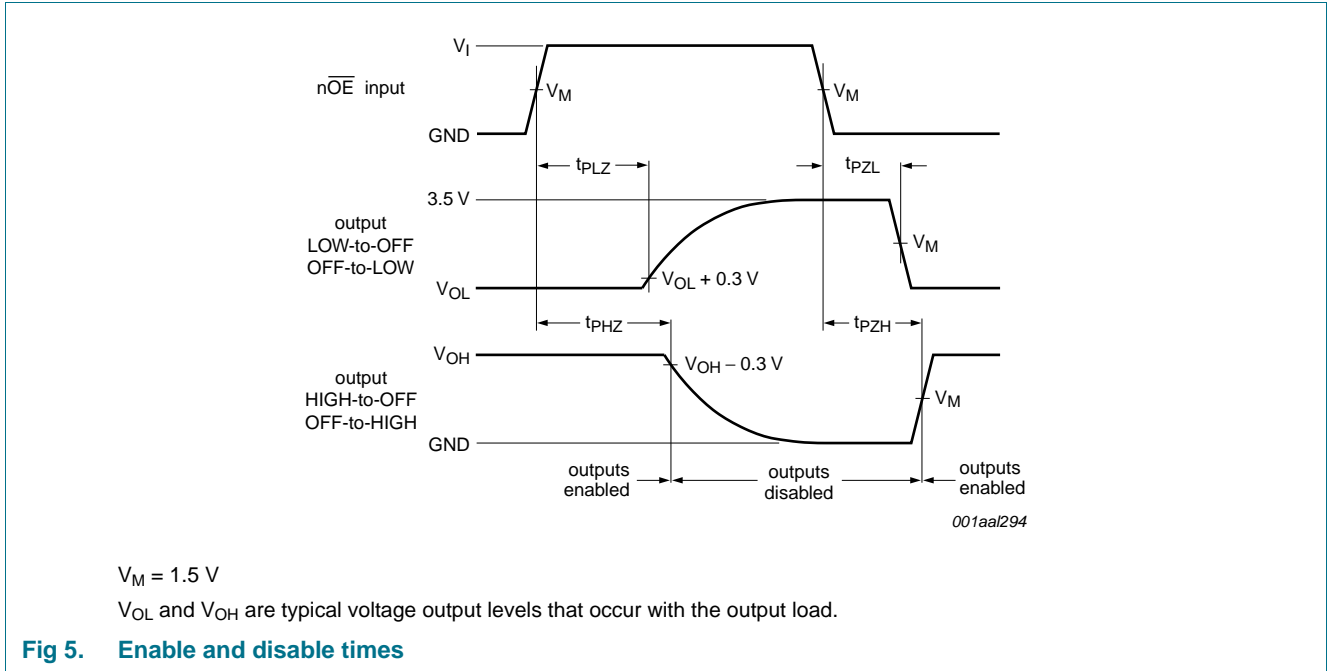


Table 8. Test data

Input				Load		V_{EXT}		
V_I	f_i	t_w	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
3.0 V	1 MHz	500 ns	$\leq 2.5\text{ ns}$	50 pF	500 Ω	open	open	7.0 V

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

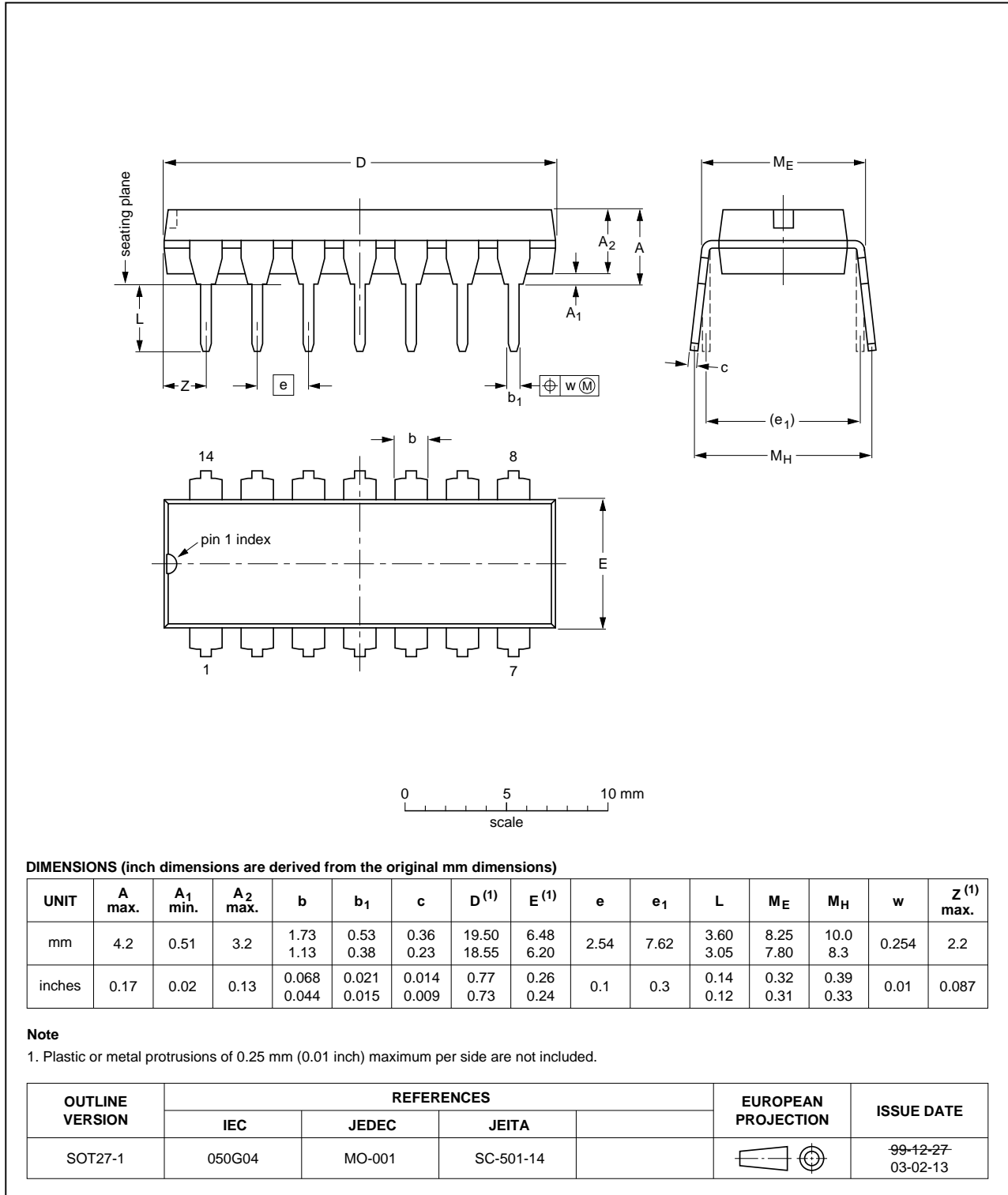


Fig 7. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

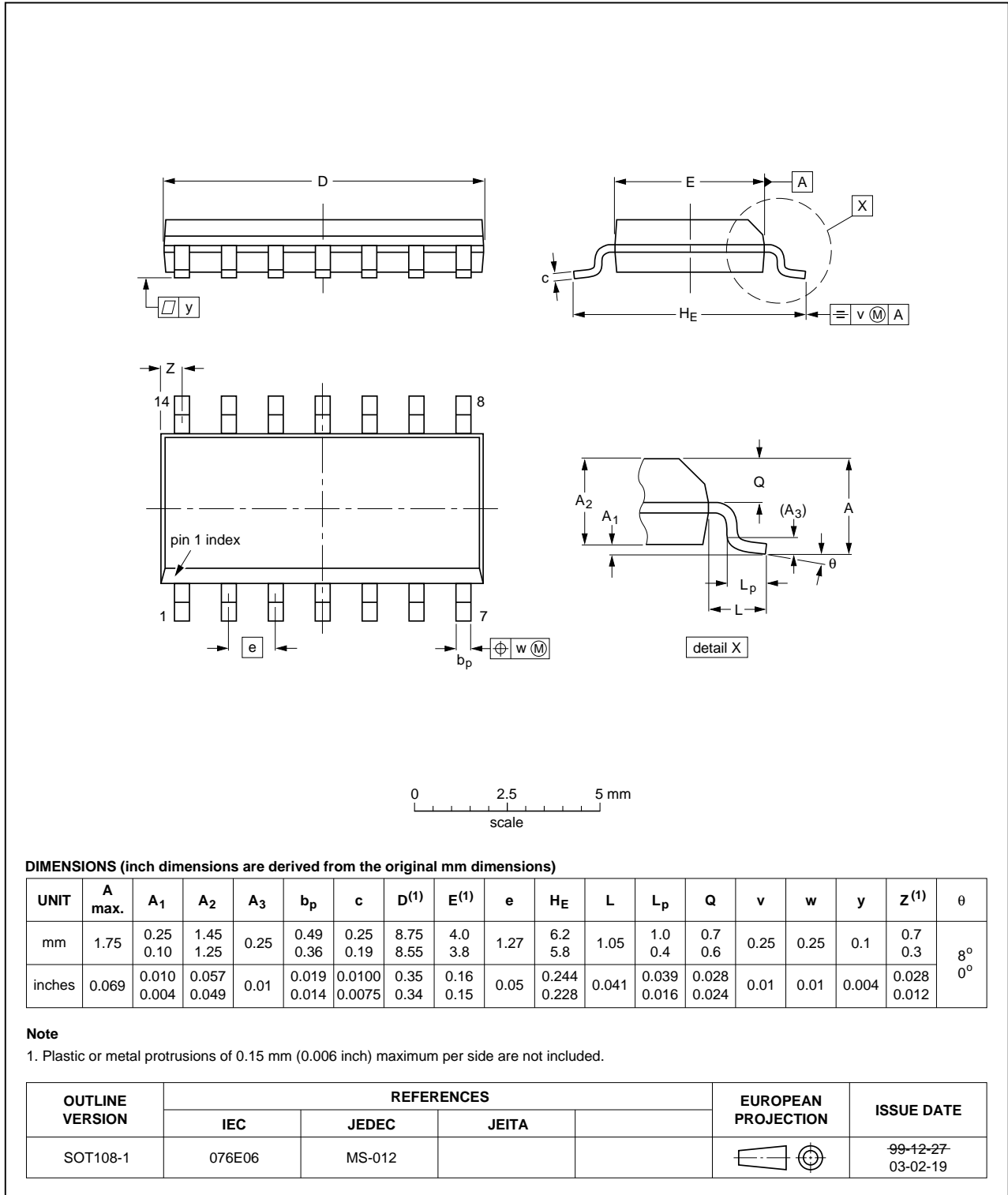


Fig 8. Package outline SOT108-1 (SO14)

13. Abbreviations

Table 9. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
LSTTL	Low-power Schottky Transistor-Transistor Logic
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
CDM	Charge-Device Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74F125 v.4	20130123	Product data sheet	-	74F125 v.3
Modifications:	<ul style="list-style-type: none"> Features and benefits: Changed mA into μA (errata). 			
74F125 v.3	20130118	Product data sheet	-	74F125 v.2
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. 			
74F125 v.2	19890328	Product data sheet	-	74F125 v.1

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

15.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

15.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond

NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

15.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

16. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

17. Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	1
4	Functional diagram	2
5	Pinning information	2
5.1	Pinning	2
5.2	Pin description	3
6	Functional description	3
7	Limiting values	3
8	Recommended operating conditions	4
9	Static characteristics	4
10	Dynamic characteristics	5
11	Waveforms	5
12	Package outline	7
13	Abbreviations	9
14	Revision history	9
15	Legal information	10
15.1	Data sheet status	10
15.2	Definitions	10
15.3	Disclaimers	10
15.4	Trademarks	11
16	Contact information	11
17	Contents	12

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP B.V. 2013.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 23 January 2013

Document identifier: 74F125